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# 74F563

## Octal D-Type Latch with 3-STATE Outputs

### General Description

The 74F563 is a high-speed octal latch with buffered common Latch Enable (LE) and buffered common Output Enable ( $\overline{OE}$ ) inputs.

This device is functionally identical to the 74F573, but has inverted outputs.

### Features

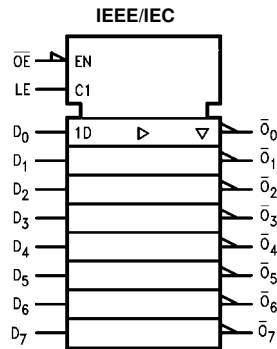
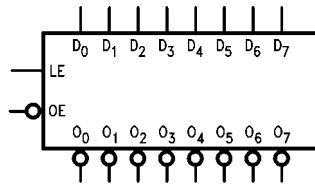
- Inputs and outputs on opposite sides of package allowing easy interface with microprocessors
- Useful as input or output port for microprocessors
- Functionally identical to 74F573

### Ordering Code:

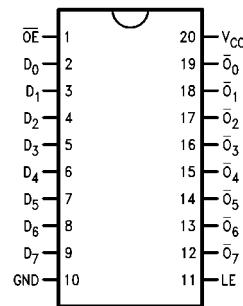
Order Number	Package Number	Package Description
74F563SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74F563SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F563PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

### Logic Symbols



### Connection Diagram



74F563 Octal D-Type Latch with 3-STATE Outputs

### Unit Loading/Fan Out

Pin Names	Description	U.L. HIGH/LOW	Input $I_{IH}/I_{IL}$ Output $I_{OH}/I_{OL}$
D <sub>0</sub> -D <sub>7</sub>	Data Inputs	1.0/1.0	20 $\mu$ A/-0.6 mA
LE	Latch Enable Input (Active HIGH)	1.0/1.0	20 $\mu$ A/-0.6 mA
$\overline{OE}$	3-STATE Output Enable Input (Active LOW)	1.0/1.0	20 $\mu$ A/-0.6 mA
$\overline{O_0}$ - $\overline{O_7}$	3-STATE Latch Outputs	150/40 (33.3)	-3 mA/24 mA (20 mA)

### Functional Description

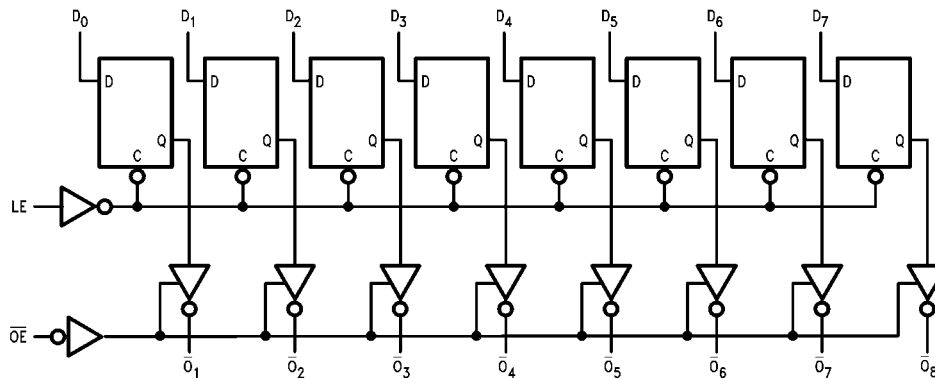
The 74F563 contains eight D-type latches with 3-STATE output buffers. When the Latch Enable (LE) input is HIGH, data on the D<sub>n</sub> inputs enters the latches. In this condition the latches are transparent, i.e., a latch output will change state each time its D input changes. When LE is LOW the latches store the information that was present on the D inputs a setup time preceding the HIGH-to-LOW transition of LE. The 3-STATE buffers are controlled by the Output Enable ( $\overline{OE}$ ) input. When  $\overline{OE}$  is LOW, the buffers are in the bi-state mode. When  $\overline{OE}$  is HIGH the buffers are in the high impedance mode but this does not interfere with entering new data into the latches.

### Function Table

Inputs			Internal	Output	Function
$\overline{OE}$	LE	D	Q	O	
H	X	X	X	Z	High Z
H	H	L	H	Z	High Z
H	H	H	L	Z	High Z
H	L	X	NC	Z	Latched
L	H	L	H	H	Transparent
L	H	H	L	L	Transparent
L	L	X	NC	NC	Latched

H = HIGH Voltage Level  
 L = LOW Voltage Level  
 X = Immaterial  
 Z = High Impedance  
 NC = No Change

### Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

**Absolute Maximum Ratings**(Note 1)

Storage Temperature	-65°C to +150°C
Ambient Temperature under Bias	-55°C to +125°C
Junction Temperature under Bias	-55°C to +150°C
V <sub>CC</sub> Pin Potential to Ground Pin	-0.5V to +7.0V
Input Voltage (Note 2)	-0.5V to +7.0V
Input Current (Note 2)	-30 mA to +5.0 mA
Voltage Applied to Output in HIGH State (with V <sub>CC</sub> = 0V)	
Standard Output	-0.5V to V <sub>CC</sub>
3-STATE Output	-0.5V to +5.5V
Current Applied to Output in LOW State (Max)	twice the rated I <sub>OL</sub> (mA)

**Recommended Operating Conditions**

Free Air Ambient Temperature	0°C to +70°C
Supply Voltage	+4.5V to +5.5V

**Note 1:** Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

**Note 2:** Either voltage limit or current limit is sufficient to protect inputs.

**DC Electrical Characteristics**

Symbol	Parameter	Min	Typ	Max	Units	V <sub>CC</sub>	Conditions
V <sub>IH</sub>	Input HIGH Voltage	2.0			V		Recognized as a HIGH Signal
V <sub>IL</sub>	Input LOW Voltage			0.8	V		Recognized as a LOW Signal
V <sub>CD</sub>	Input Clamp Diode Voltage			-1.2	V	Min	I <sub>IN</sub> = -18 mA
V <sub>OH</sub>	Output HIGH Voltage	10% V <sub>CC</sub> 10% V <sub>CC</sub> 5% V <sub>CC</sub> 5% V <sub>CC</sub>	2.5 2.4 2.7 2.7		V	Min	I <sub>OH</sub> = -1 mA I <sub>OH</sub> = -3 mA I <sub>OH</sub> = -1 mA I <sub>OH</sub> = -3 mA
V <sub>OL</sub>	Output LOW Voltage	10% V <sub>CC</sub>		0.5	V	Min	I <sub>OL</sub> = 24 mA
I <sub>IH</sub>	Input HIGH Current			5.0	μA	Max	V <sub>IN</sub> = 2.7V
I <sub>BVI</sub>	Input HIGH Current Breakdown Test			7.0	μA	Max	V <sub>IN</sub> = 7.0V
I <sub>CEx</sub>	Output HIGH Leakage Current			50	μA	Max	V <sub>OUT</sub> = V <sub>CC</sub>
V <sub>ID</sub>	Input Leakage Test	4.75			V	0.0	I <sub>ID</sub> = 1.9 μA All Other Pins Grounded
I <sub>OD</sub>	Output Leakage Circuit Current			3.75	μA	0.0	V <sub>IOD</sub> = 150 mV All Other Pins Grounded
I <sub>IL</sub>	Input LOW Current			-0.6	mA	Max	V <sub>IN</sub> = 0.5V
I <sub>OZH</sub>	Output Leakage Current			50	μA	Max	V <sub>OUT</sub> = 2.7V
I <sub>OZL</sub>	Output Leakage Current			-50	μA	Max	V <sub>OUT</sub> = 0.5V
I <sub>OS</sub>	Output Short-Circuit Current	-60		-150	mA	Max	V <sub>OUT</sub> = 0V
I <sub>ZZ</sub>	Bus Drainage Test			500	μA	0.0V	V <sub>OUT</sub> = 5.25V
I <sub>CC1</sub>	Power Supply Current		40	61	mA	Max	V <sub>O</sub> = LOW
I <sub>CC2</sub>	Power Supply Current		40	61	mA	Max	V <sub>O</sub> = HIGH Z

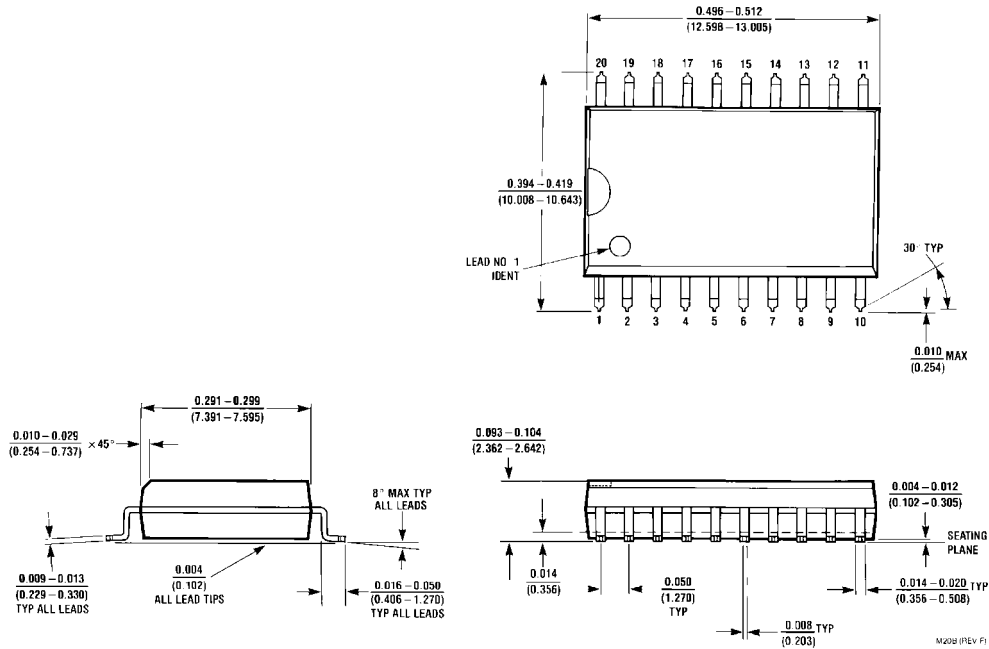
### AC Electrical Characteristics

Symbol	Parameter	$T_A = +25^\circ\text{C}$ $V_{CC} = +5.0\text{V}$ $C_L = 50\text{ pF}$		$T_A = -55^\circ\text{C to } +125^\circ\text{C}$ $V_{CC} = +5.0\text{V}$ $C_L = 50\text{ pF}$		$T_A = 0^\circ\text{C to } +70^\circ\text{C}$ $V_{CC} = +5.0\text{V}$ $C_L = 50\text{ pF}$		Units	
		Min	Typ	Max	Min	Max	Min		Max
$t_{PLH}$	Propagation Delay	3.5		8.5	3.0	10.5	3.0	9.5	ns
$t_{PHL}$	$D_n$ to $\overline{O}_n$	2.5		6.5	2.0	7.5	2.0	7.0	
$t_{PLH}$	Propagation Delay	4.5		9.5	4.0	11.0	4.0	10.5	ns
$t_{PHL}$	LE to $\overline{O}_n$	3.0		7.0	2.5	7.5	2.5	7.0	
$t_{PZH}$	Output Enable Time	2.0		7.5	2.0	9.5	2.0	9.0	ns
$t_{PZL}$		3.0		8.5	2.5	10.0	1.5	9.5	
$t_{PHZ}$	Output Disable Time	1.5		5.5	1.5	7.0	1.5	6.5	ns
$t_{PLZ}$		1.5		5.5	1.5	5.5	1.5	5.5	

### AC Operating Requirements

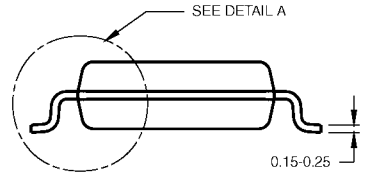
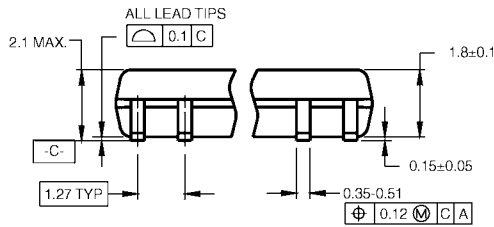
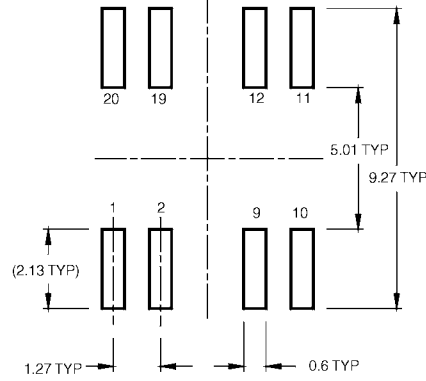
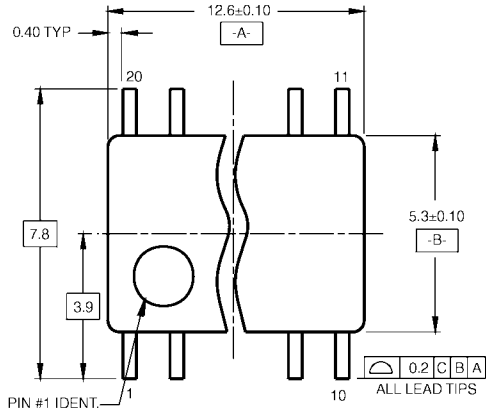
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		Min	Max	Min	Max	Min	Max	
$t_S(H)$	Setup Time, HIGH or LOW	2.0		2.0		2.0		ns
$t_S(L)$	$D_n$ to LE	2.0		2.0		2.0		
$t_H(H)$	Hold Time, HIGH or LOW	3.0		3.0		3.0		ns
$t_H(L)$	$D_n$ to LE	3.0		3.0		3.0		
$t_W(H)$	LE Pulse Width, HIGH	4.0		4.0		4.0		ns

**Physical Dimensions** inches (millimeters) unless otherwise noted



**20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide  
Package Number M20B**

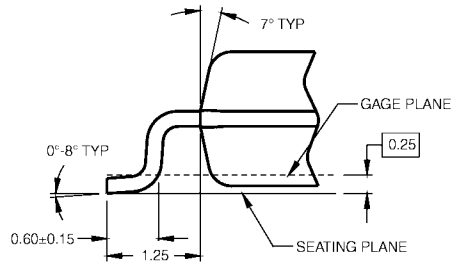
**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



DIMENSIONS ARE IN MILLIMETERS

- NOTES:  
 A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.  
 B. DIMENSIONS ARE IN MILLIMETERS.  
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

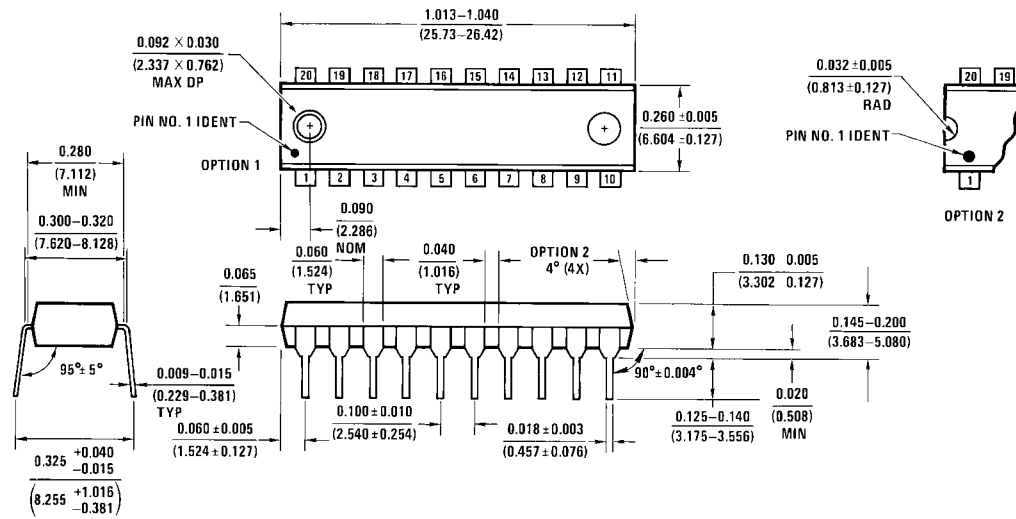
M20DRevB1



DETAIL A

**20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide Package Number M20D**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



N20A (REV G)

**20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide  
Package Number N20A**

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